## **DB2S205**

## Silicon epitaxial planar type

For high speed switching circuits

#### ■ Features

- ullet Low forward voltage  $V_F$
- Short reverse recovery time t<sub>rr</sub>
- Halogen-free / RoHS compliant
   (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

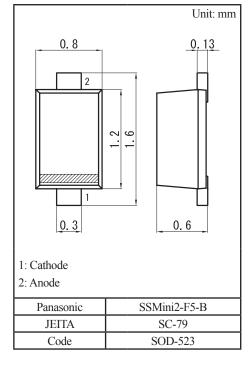
#### ■ Marking Symbol: BA

#### Packaging

DB2S20500L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Reverse voltage	V <sub>R</sub>	20	V	
Repetitive peak reverse voltage	V <sub>RRM</sub>	15	V	
Forward current (Average)	I <sub>F(AV)</sub>	200	mA	
Peak forward current	$I_{FM}$	300	mA	
Non-repetitive peak forward surge current *	I <sub>FSM</sub>	1	A	
Junction temperature	$T_j$	125	°C	
Storage temperature	T <sub>stg</sub>	-55 to +125	°C	



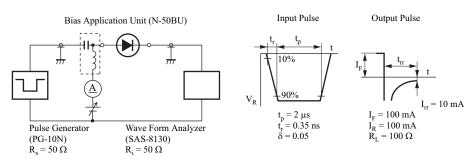
Note) \*: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

### ■ Electrical Characteristics $T_a = 25$ °C±3°C

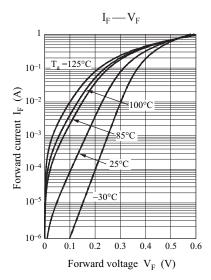
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F</sub>	$I_F = 200 \text{ mA}$			0.39	V
Reverse current	$I_R$	$V_R = 6 V$			50	μΑ
Terminal capacitance	C <sub>t</sub>	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		6.1		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}, I_{rr} = 10 \text{ mA},$ $R_L = 100 \Omega$		2.2		ns

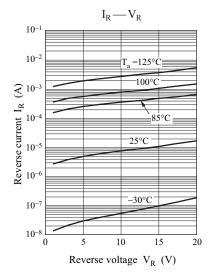
 $Note) \ 1. \ Measuring \ methods \ are \ based \ on \ JAPANESE \ INDUSTRIAL \ STANDARD \ JIS \ C \ 7031 \ measuring \ methods \ for \ diodes.$ 

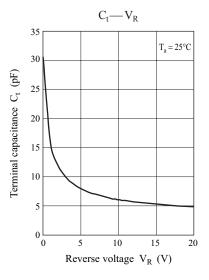
- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is  $250\ \text{MHz}$ 
  - \*: t<sub>rr</sub> measurement circuit



## **Panasonic**



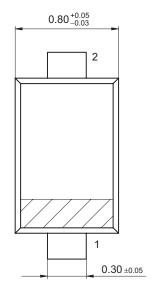


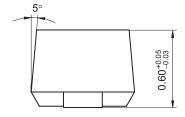


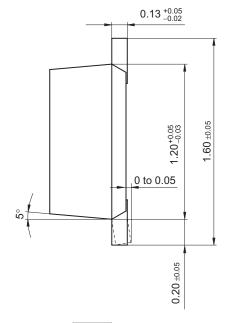
2 Ver. DED

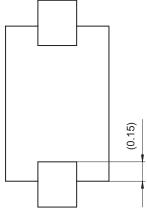
SSMini2-F5-B

Unit: mm

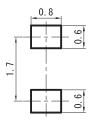








■ Land Pattern (Reference) (Unit: mm)



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